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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/556,398	11/10/2005	François Droz	90500-000067/US	6278	
90593 7590 94282011 HARNESS, DICKEY & PIERCE, P.L.C. P.O. BOX 8910			EXAMINER		
			MAI, THIEN T		
RESTON, VA	20195		ART UNIT PAPER NUMBER		
			2887		
			MAIL DATE	DELIVERY MODE	
			04/28/2011	PAPER	

Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

Application No. Applicant(s) DROZ, FRANCOIS 10/556,398 Office Action Summary Examiner Art Unit

		THIEN T. MAI	2887					
The MAILING DATE of this communication appears on the cover sheet with the correspondence address Period for Reply								
A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MALLING DATE. OF THIS COMMUNICATION. Elements of time may be available under the provision of 37 OFEI 1 136(). In no event, however, may a reply be timely lifed after SX (6) MONTHS from the mailing date of this communication. If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication. Failure to reply within the set or extended period for reply will, by statutie, cause the application to become ARMONDED (SG U.S.C.§ 133). Failure to reply within the set or extended period for reply will, statuting the set of the communication, even through filled, may reflect be a set of the communication.								
Status								
2a)	Responsive to communication(s) filed on $\underline{02F_6}$ This action is FINAL . $2b)$ This Since this application is in condition for allowar closed in accordance with the practice under E	action is non-final. nce except for formal matters, pro		e merits is				
Dienociti	ion of Claims							
4) 🖂 5) 🗀 6) 🖂 7) 🗀	A Claim(s) 1.2.6 and 9.21 is/are pending in the application. A Of the above claim(s) 15.21 is/are withdrawn from consideration. Claim(s) is/are allowed. Claim(s) is/are allowed. Claim(s) is/are objected. Claim(s) is/are objected to. Claim(s) are subject to restriction and/or election requirement.							
Applicati	ion Papers							
9) ☐ The specification is objected to by the Examiner. 10) ☒ The drawing(s) filed on 10 November 2005 is/are: a) ☒ accepted or b) ☐ objected to by the Examiner. Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a). Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d). 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.								
Priority (under 35 U.S.C. § 119							
a)l	Acknowledgment is made of a claim for foreign All b) □ Some * c) □ None of: 1. □ Certified copies of the priority documents 2. □ Certified copies of the priority documents 3. □ Copies of the certified copies of the prior application from the International Bureau See the attached detailed Office action for a list	s have been received. s have been received in Applicati- ity documents have been receive u (PCT Rule 17.2(a)).	on No ed in this National	Stage				
Attachmen	nt(s) te of References Cited (PTO-892)	4) Interview Summary	(PTO-413)					

Paper No(s)/IVall Date Notice of Draftsperson's Patent Drawing Review (PTO 948)
 Information Disclosure Statement(s) (PTO/SB/08) 5) Notice of Informal Patent Application Paper No(s)/Mail Date _____ 6) Other: __

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DETAILED ACTION

Acknowledgement

Acknowledgement is hereby made of Amendment filed 2/02/2011.

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this little; if the differences between the subject matter south of the patent and set prior and are such start in the subject matter south with the patent and set prior and are such start in the subject matter south with the patent south and so the subject matter south and so that so that so that so the subject matter so that so tha

The factual inquiries set forth in *Graham v. John Deere Co.*, 383 U.S. 1, 148 USPQ 459 (1966), that are applied for establishing a background for determining obviousness under 35 U.S.C. 103(a) are summarized as follows:

- Determining the scope and contents of the prior art.
- Ascertaining the differences between the prior art and the claims at issue.
- 3. Resolving the level of ordinary skill in the pertinent art.
- Considering objective evidence present in the application indicating obviousness or nonobviousness.
- Claims 1-2, 9 are rejected under 35 U.S.C. 103(a) as being unpatentable over DE 19645083 A1 (DE'083 hereinafter)

Re claim 1, *DE'083* discloses a process for assembling at least one electronic component made up of a chip provided with contacts on one of the faces of the chip, said contacts being set off on a conductive film constituting flat conductive areas that extend the contacts of the chip in a plane over the chip, the conductive areas being connected to conductive tracks placed on a surface of a planar insulating substrate, comprising:

placing the substrate on a work surface, the face including conductive tracks (i.e. antenna coil
 10) being oriented upwards (Figs. 4.8).

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 placing the electronic component (7) into a cavity of the substrate situated in a zone including the conductive tracks, the chip being inserted into the cavity, the conductive areas (9) of the electronic component coming into contact with the corresponding conductive tracks of the substrate (Fig. 1-2), and

 forming a layer of insulating material (silicon rubber 6; Fig. 1) which extends concurrently on the electronic component and at least on the zone of the substrate surrounding said electronic component,

wherein the conductive areas (9) of the electronic component and the conductive tracks of the substrate are in contact to achieve an electric connection via a pressure of application of the insulating material layer on the electronic component (Fig. 1-2), and

after forming the layer of insulating material, the contacted conductive areas of the electronic component and the conductive tracks of the substrate are configured to rub together when repeated stressed are exerted on the substrate

(DE'083 is silent to the rubbing; however, DE'083 teaches "these through-connection of the contact surfaces of the transponder coil is to the contact surfaces of the chip module on a resistive contact element, which consists for example of a pressure-sensitive conductive silicone rubber, which is as a contact material in the space between the two opposing contact surfaces, and once the air gap between the contact surfaces is compressed, said contact element is used both in direct ohmic contact with the contact surfaces of the transponder coil and with the opposed contact surfaces of the chip module" (page 8). Since silicon has been well know for its flexibility, it would have been obvious to one of ordinary skill in the art at the time the invention was made that they rub together due to available space surrounding the electronic component and/or chip and/or the flexibility of the silicon rubber material.)

Re claim 2, the electronic component is coated by an insulating material on the face of the chip opposite to the face provided with contacts (i.e. page 12, 13).

Re claim 9, the cavity is formed by milling or by stamping a window (page 12).

Claim 6 is rejected under 35 U.S.C. 103(a) as being unpatentable over DE 19645083 A1 (DE'083 hereinafter) in view of Ikeda (JP 01020197 A)..

DE'083's teachings have been discussed above.

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DE'083 is unclear with respect to heating the chip before inserting into the cavity. Ikeda discloses the electronic component is obtained by heating the chip of the electronic component with a mold section 9 resulting in heat dissipation before inserting into the cavity along with aluminum foils 4 (Fig. 1-2, see abstract).

Therefore, it would have been obvious to one of ordinary skill in the art at the time the invention was made to incorporate the teachings of Ikeda for achieving better productivity and production speed by inserting the component into the cavity after being molded while still being warm resulted from the heated mold.

Remarks

Applicant's arguments have been considered but are moot in view of the new ground(s) of rejection.

The prior art made of record and not relied upon is considered pertinent to applicant's disclosure: see Tanaka in PTO-892, which discloses a switch.

The Examiner has pointed out particular references contained in the prior art of record within the body of this action for the convenience of the applicant. Applicant, in preparing the response, should consider fully the entire references as potentially teaching all or part of the claimed invention, as well as the context of the passage as taught by the prior art or disclosed by the Examiner.

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to THIEN T. MAI whose telephone number is (571)272-8283. The examiner can normally be reached on Monday through Friday, 8:00 - 5:00PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Steve S. Paik can be reached on 571-272-2404. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

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Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

/Thien T Mai/ Examiner, Art Unit 2887